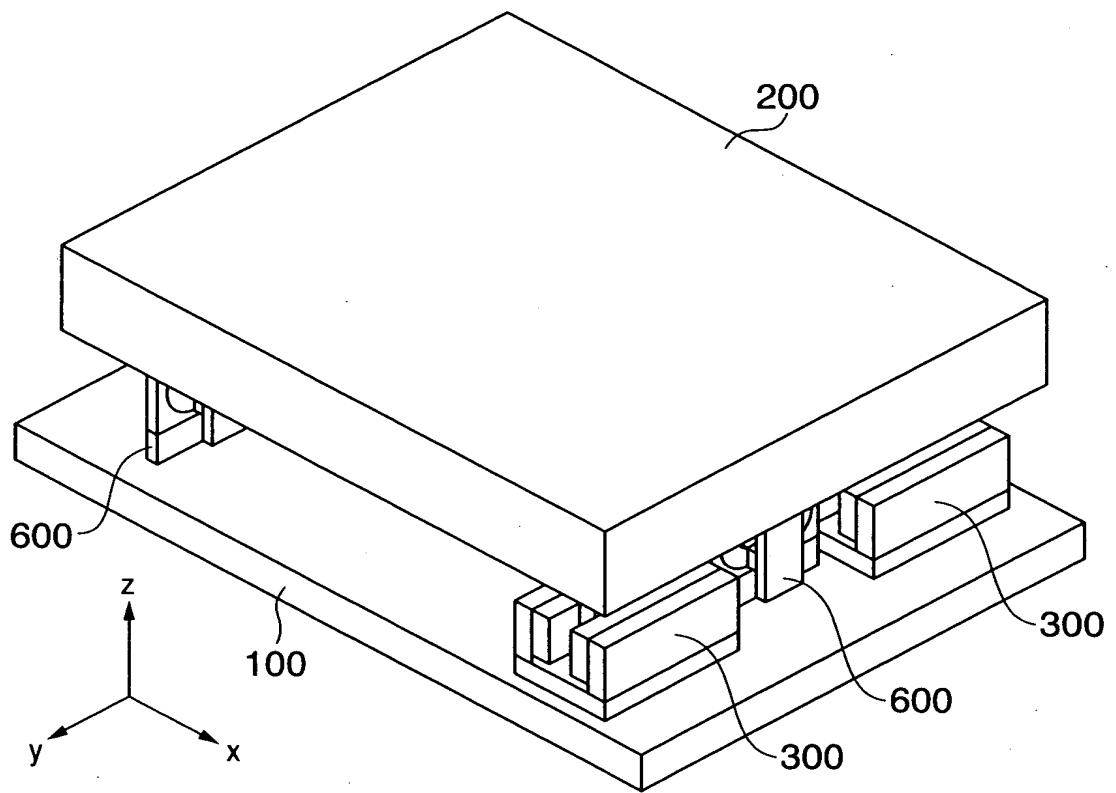
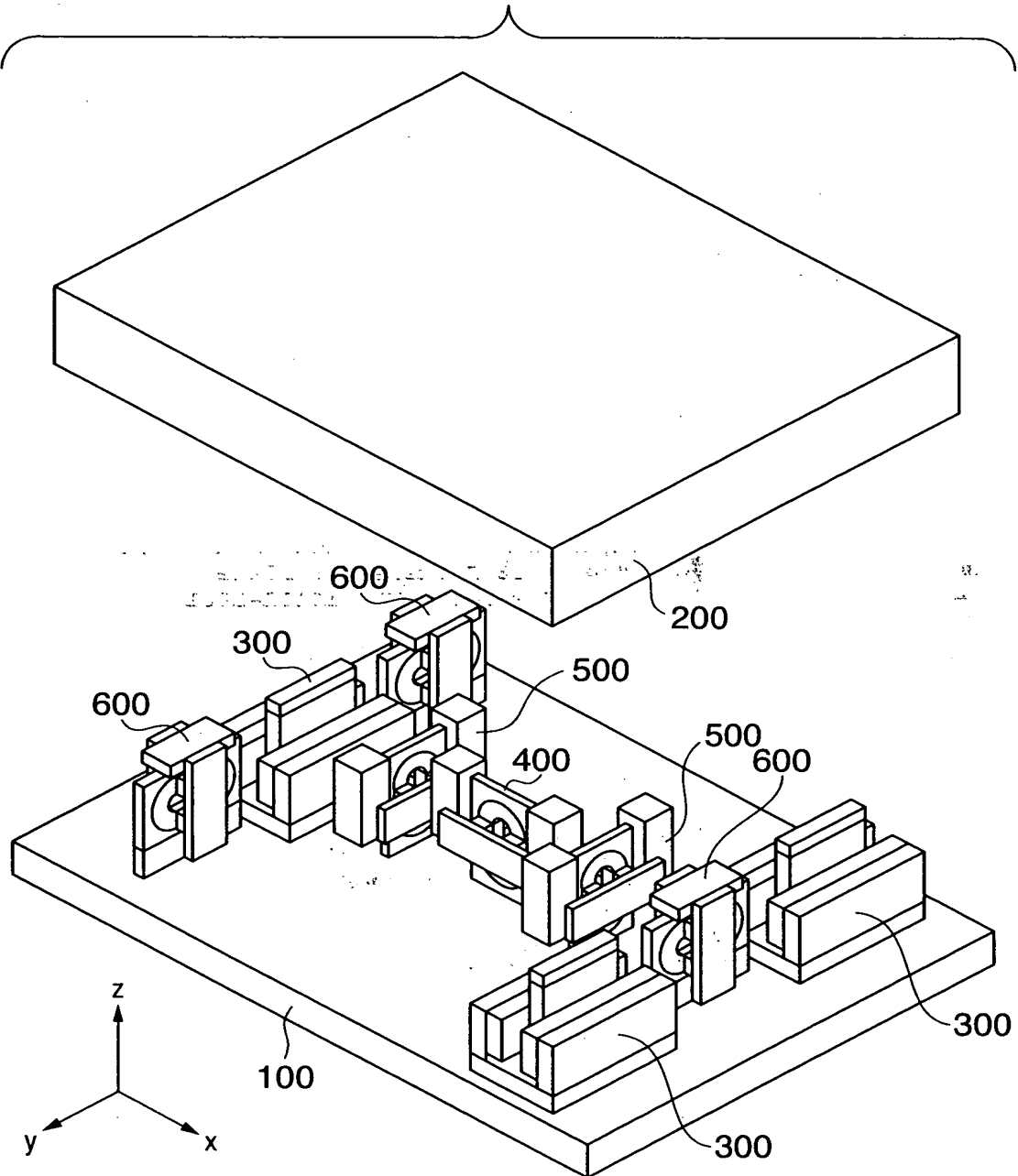
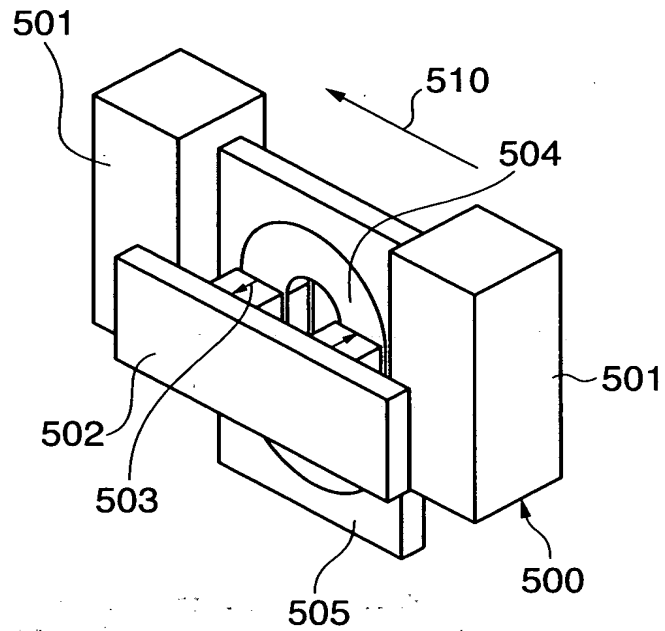


**FIG. 1**

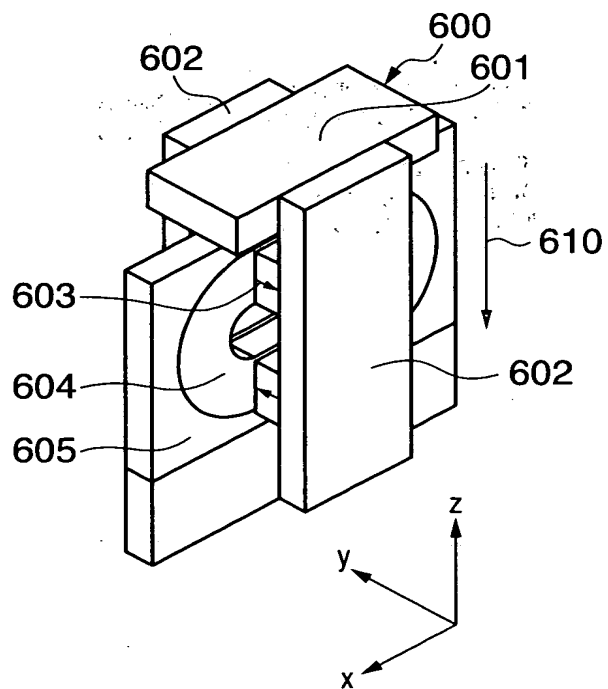
**FIG. 2**

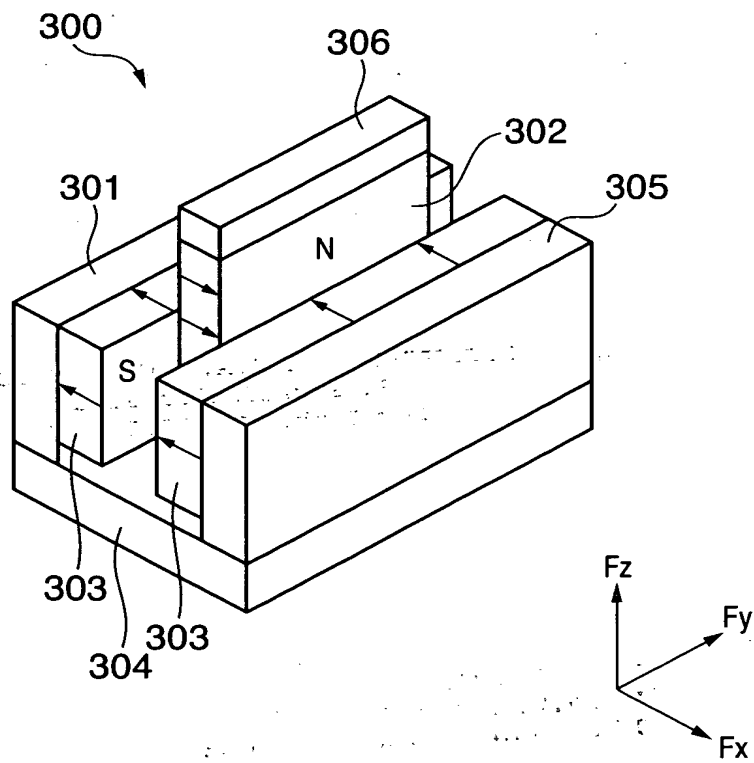
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**FIG. 3A**



**FIG. 3B**



**FIG. 4A**

# FIG. 4B

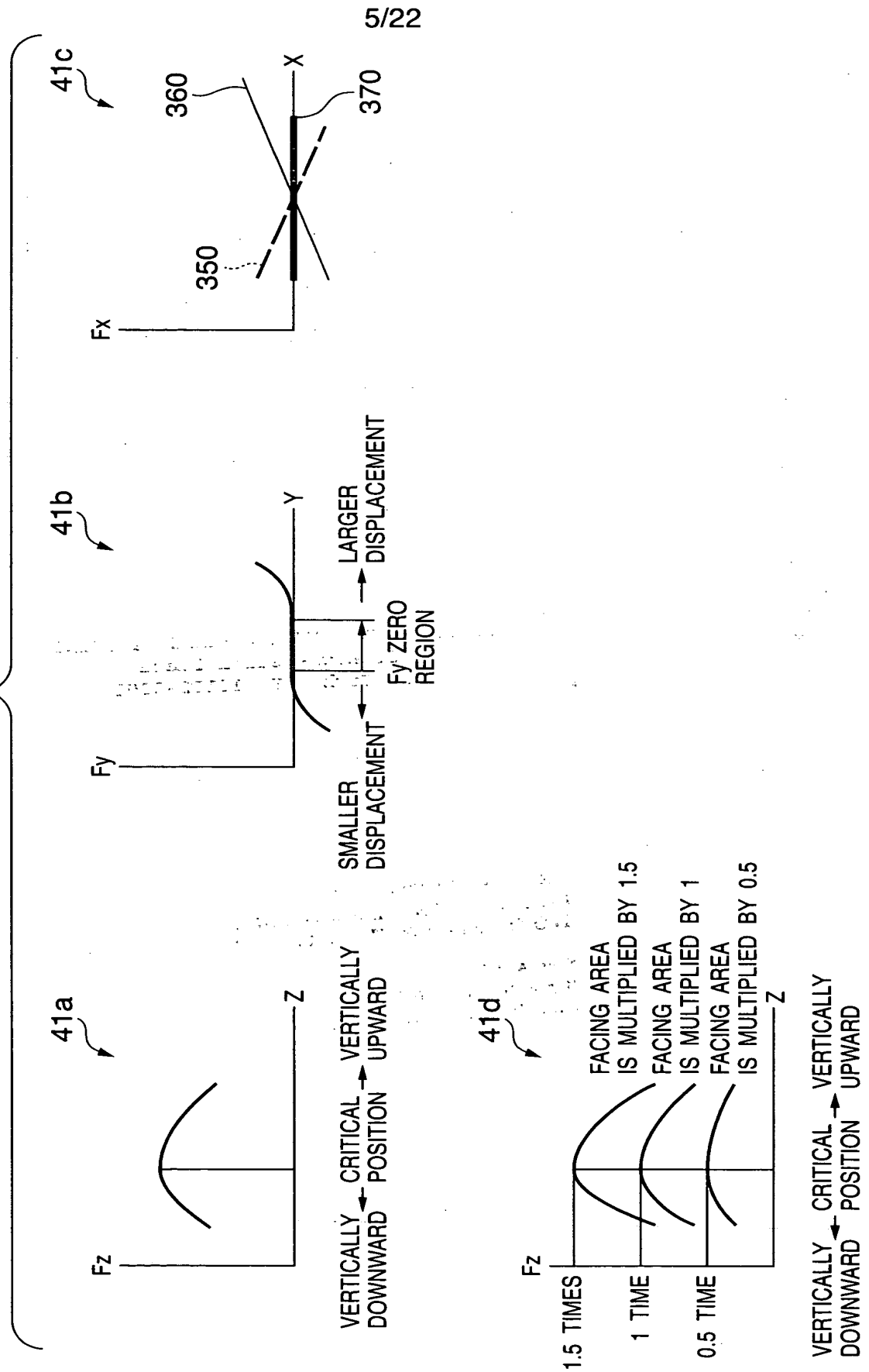


FIG. 5

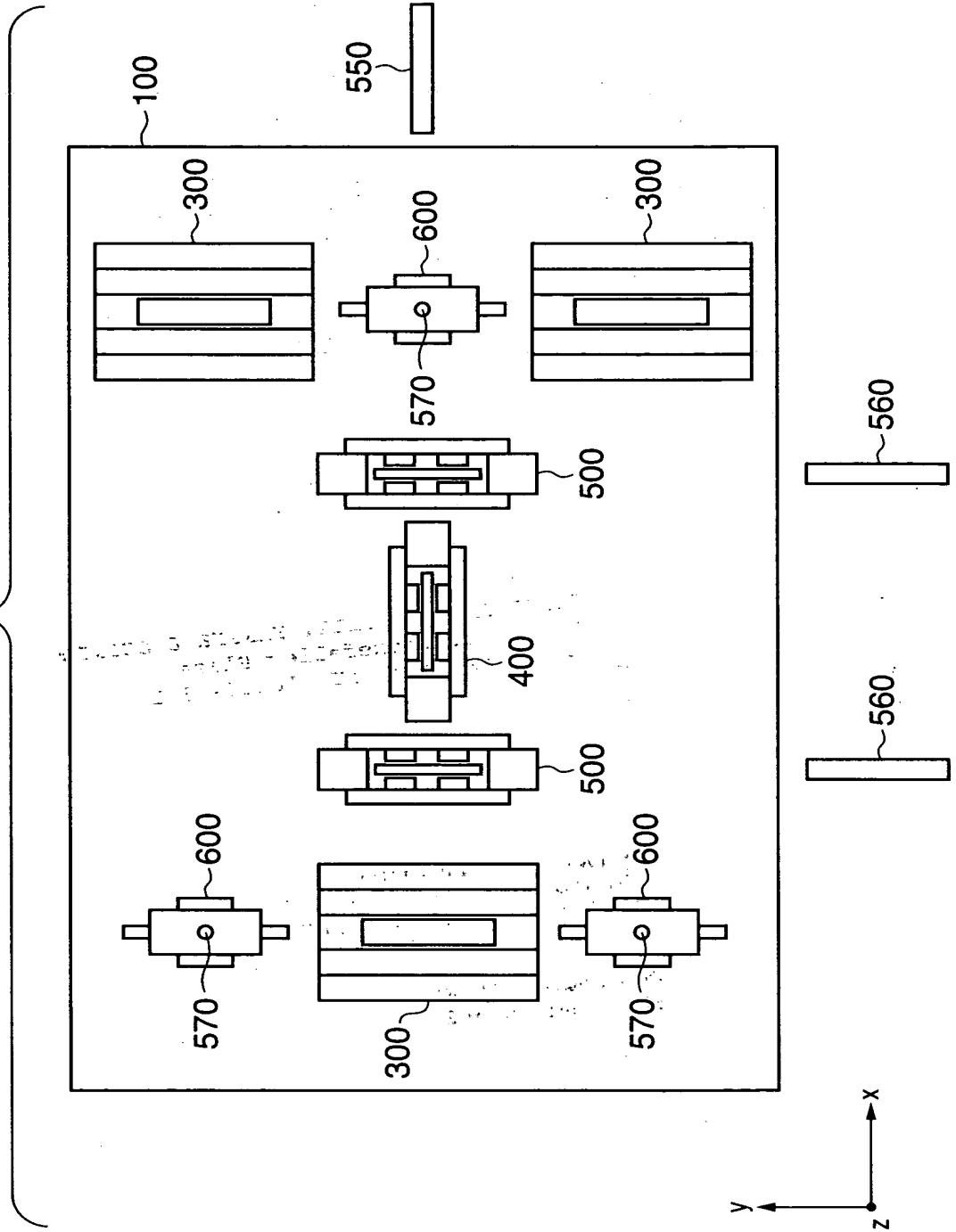
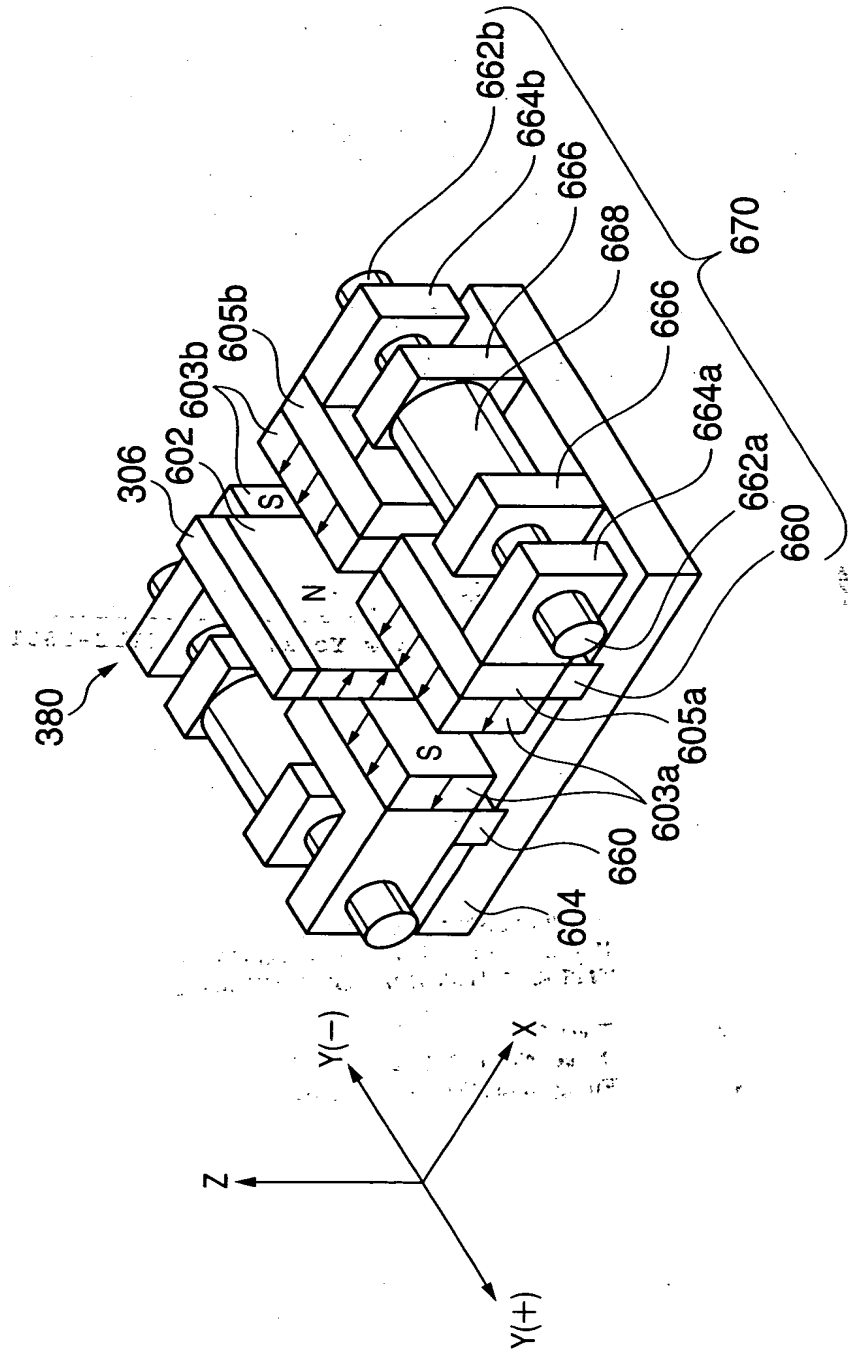
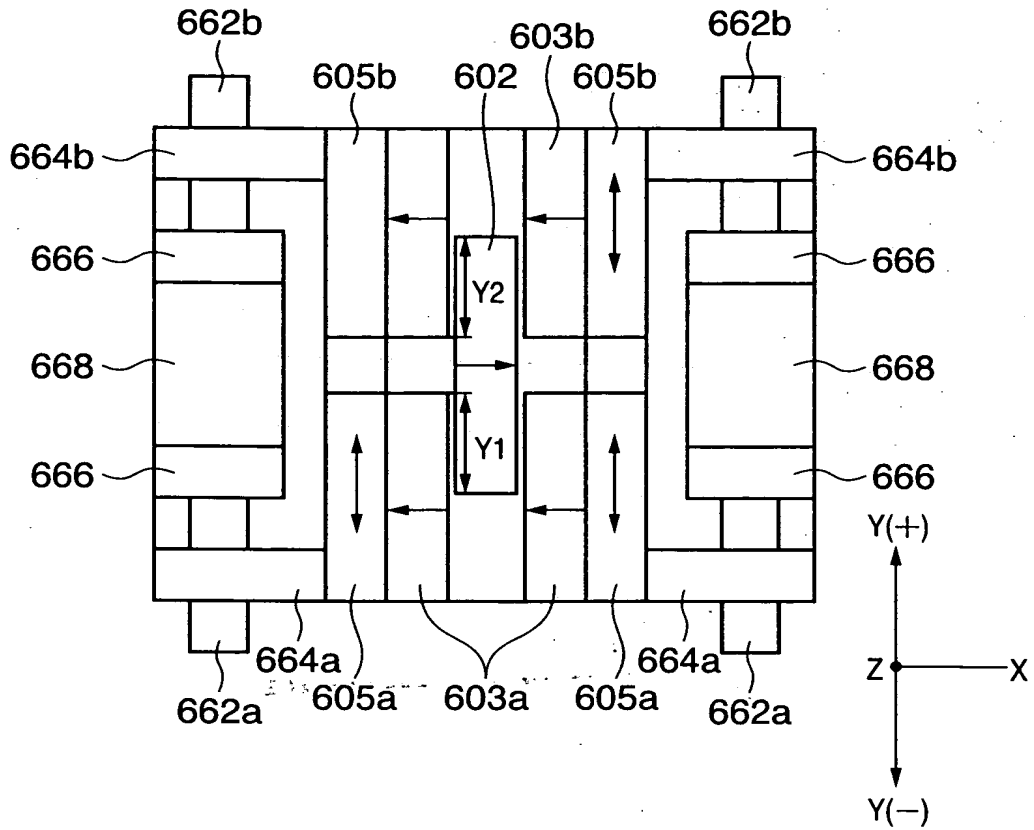


FIG. 6A



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**FIG. 6B**



**FIG. 6C**

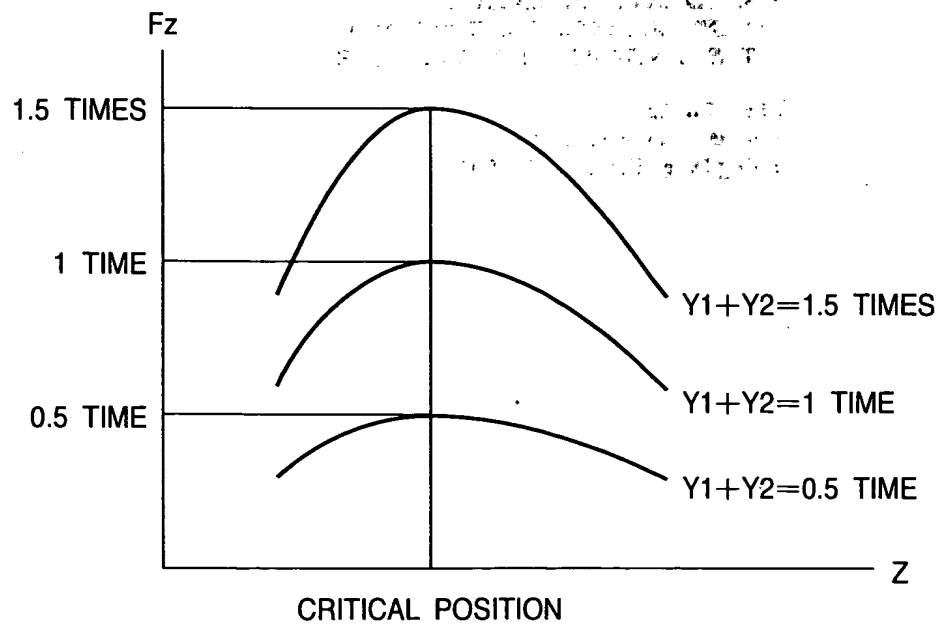




FIG. 6D

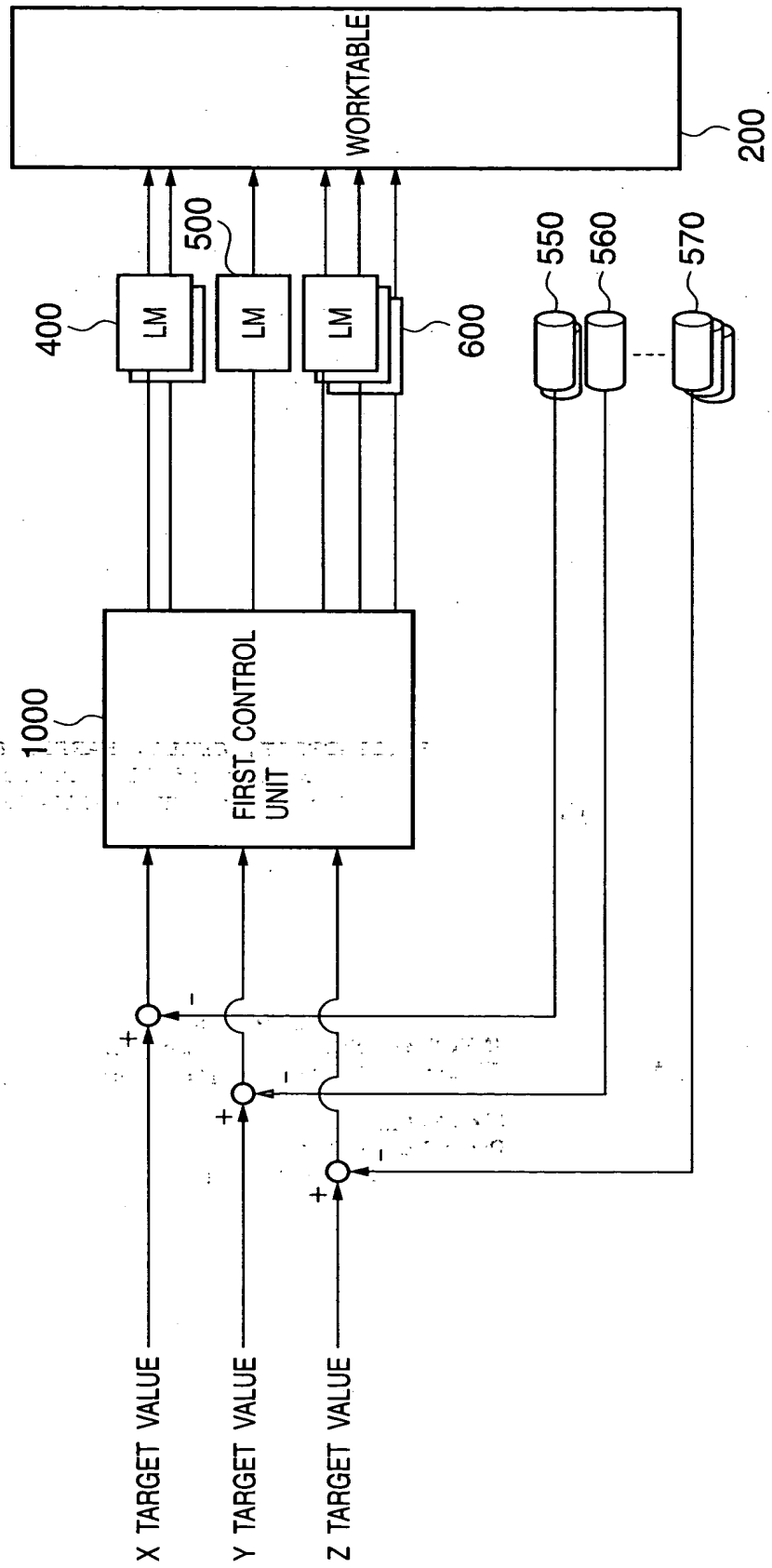
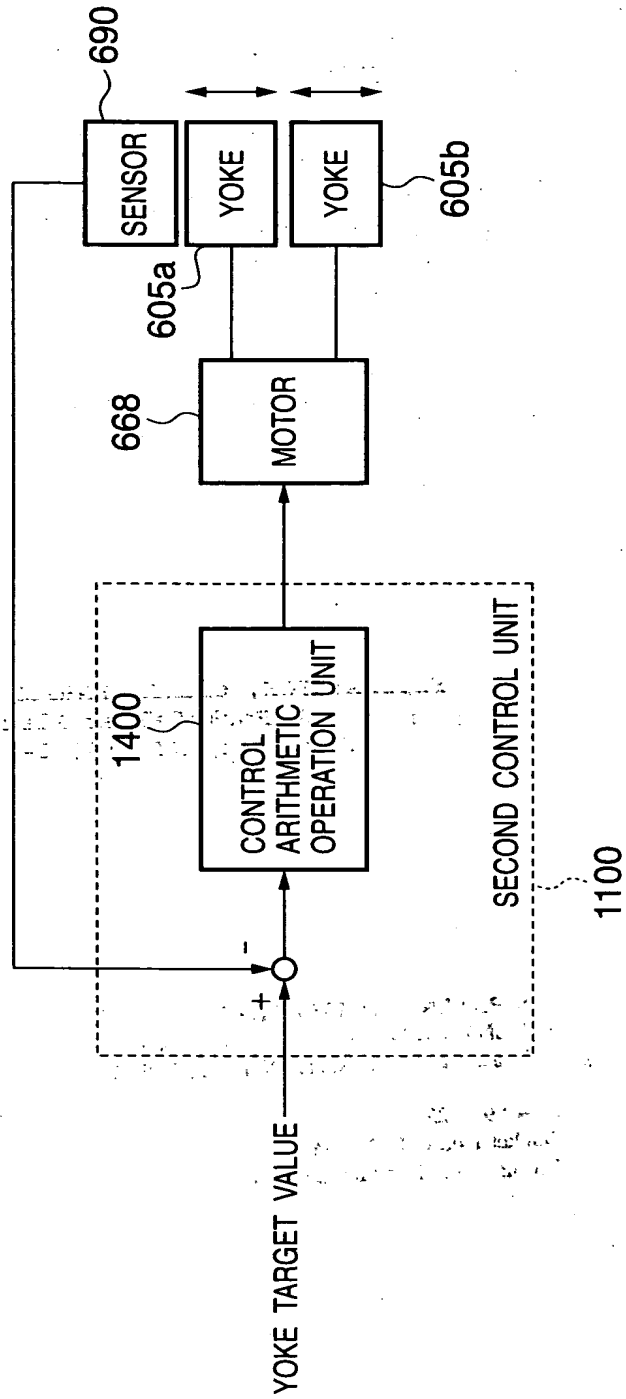
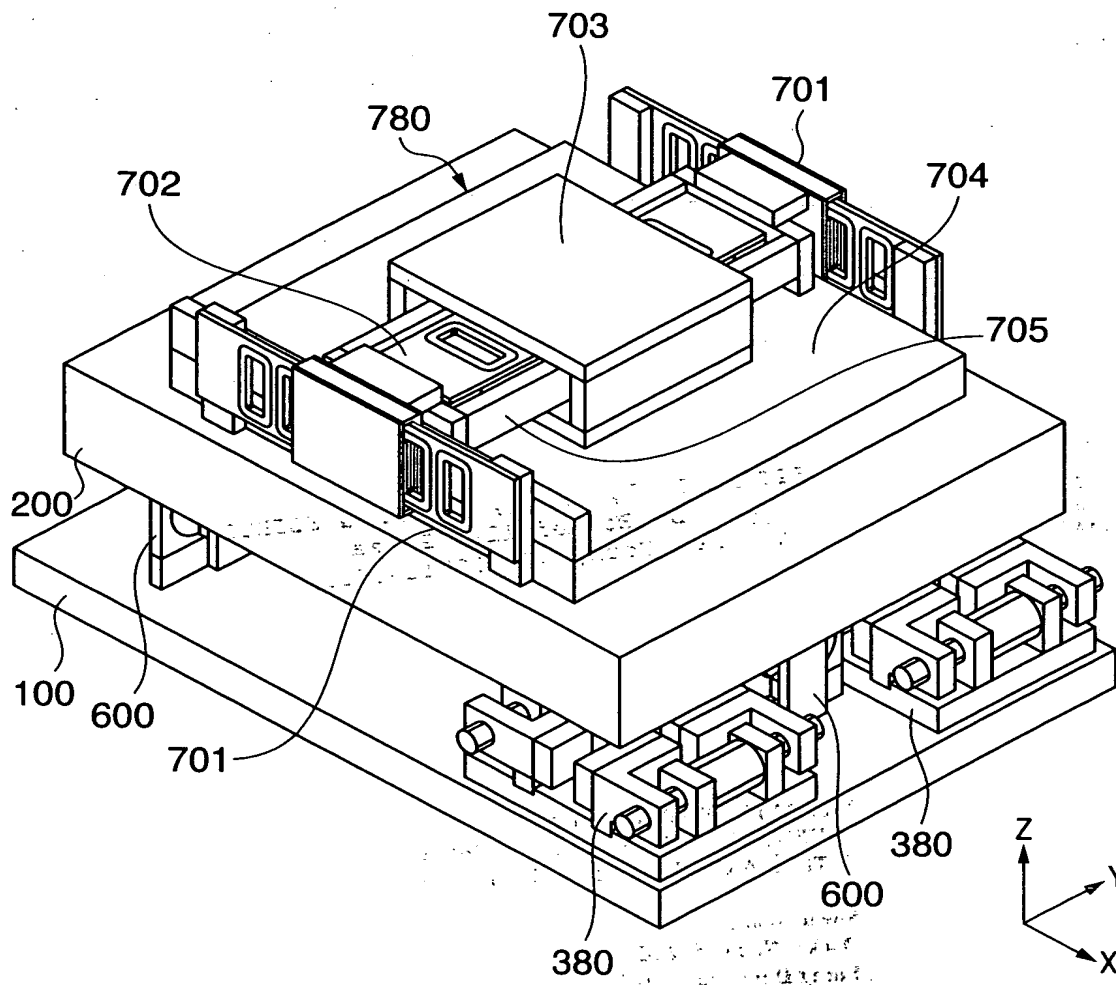


FIG. 6E



**FIG. 7**

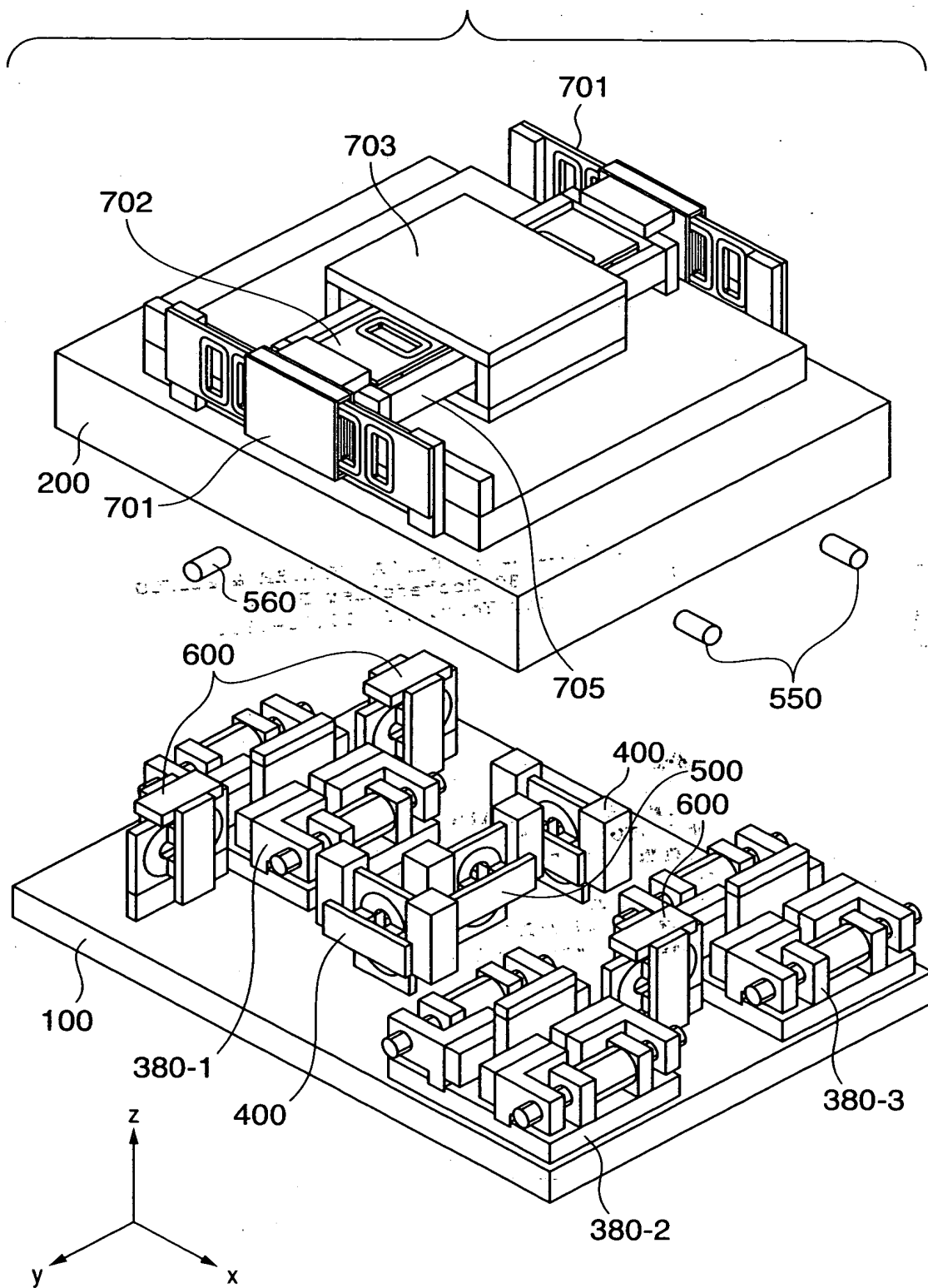


FIG. 9

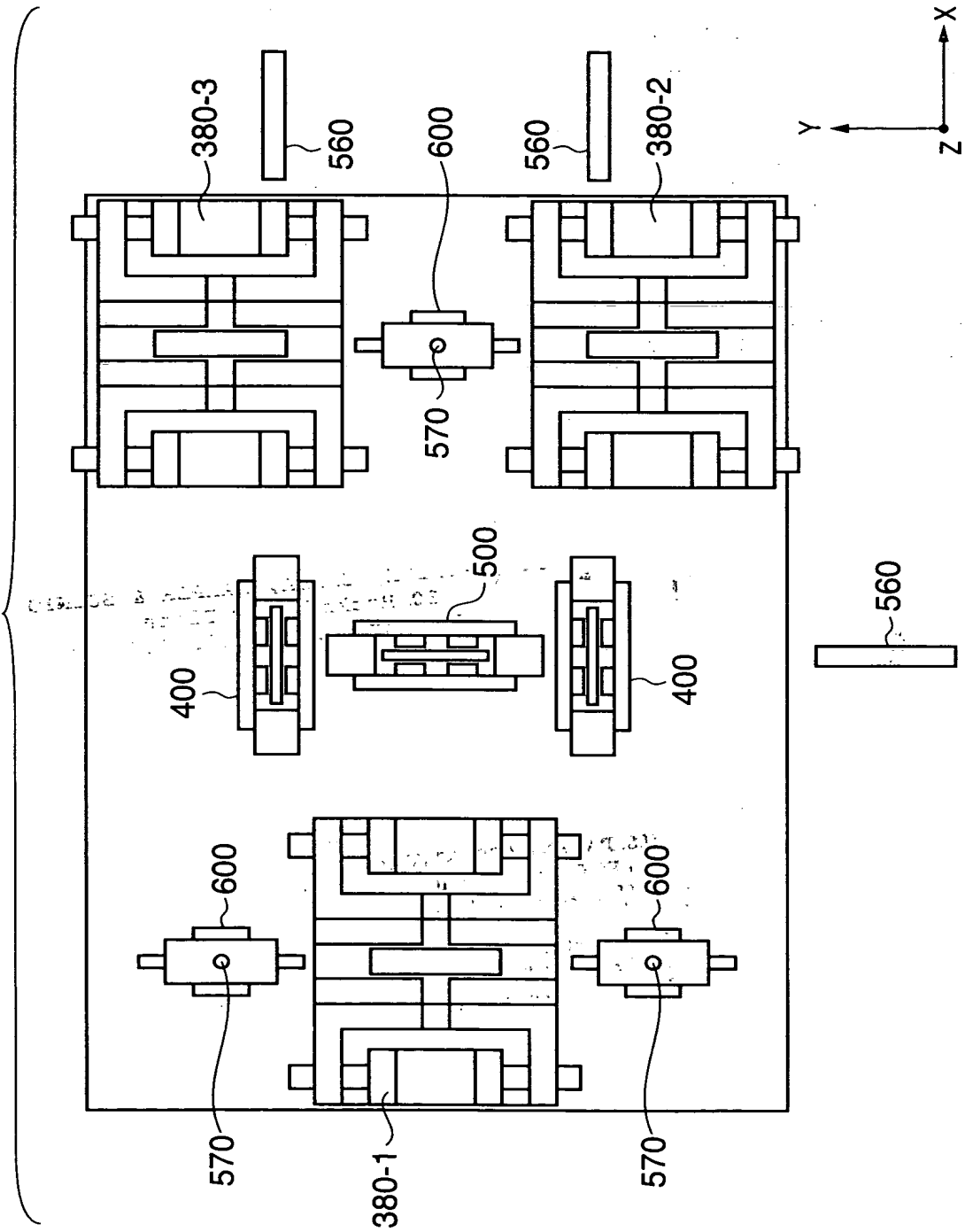
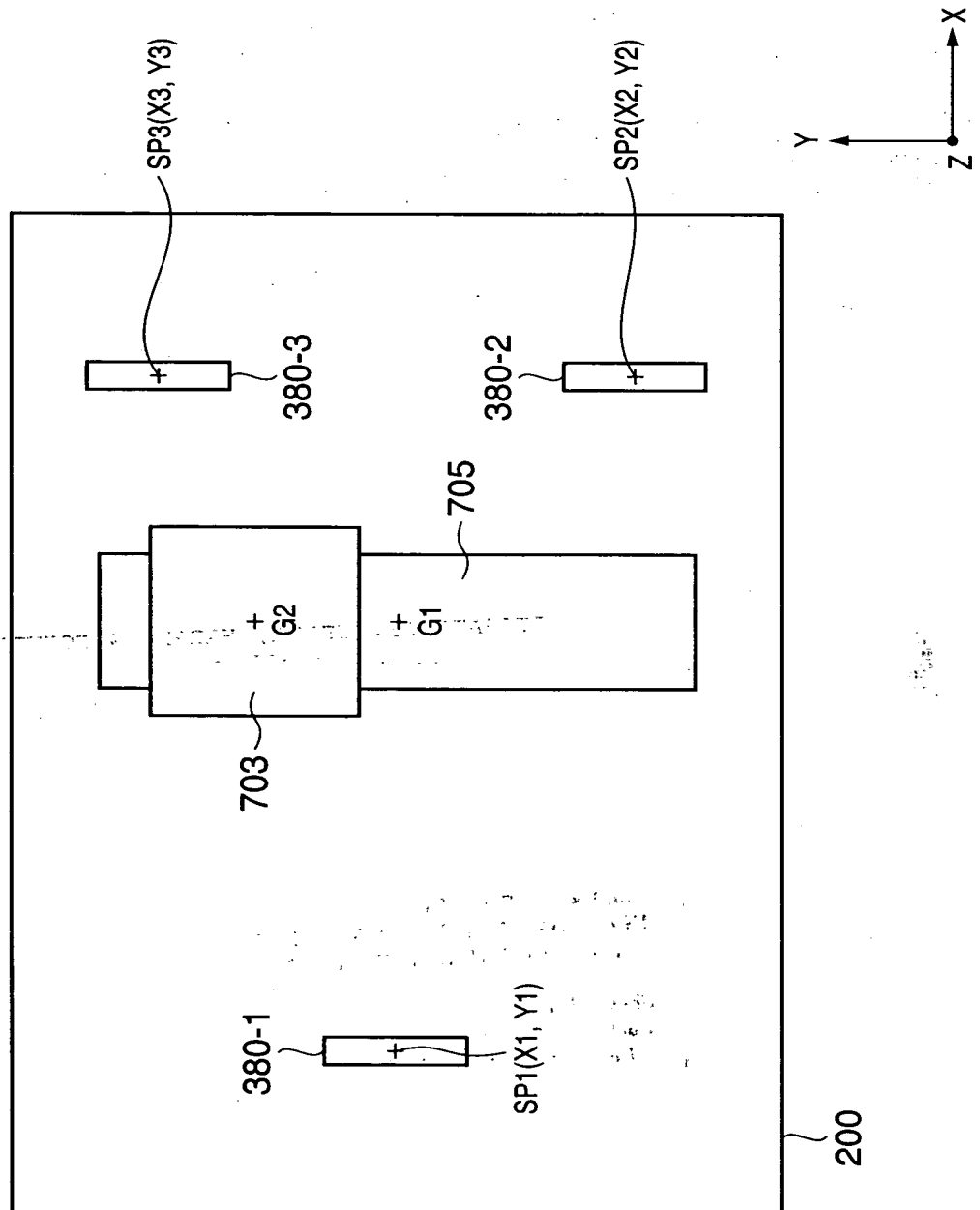
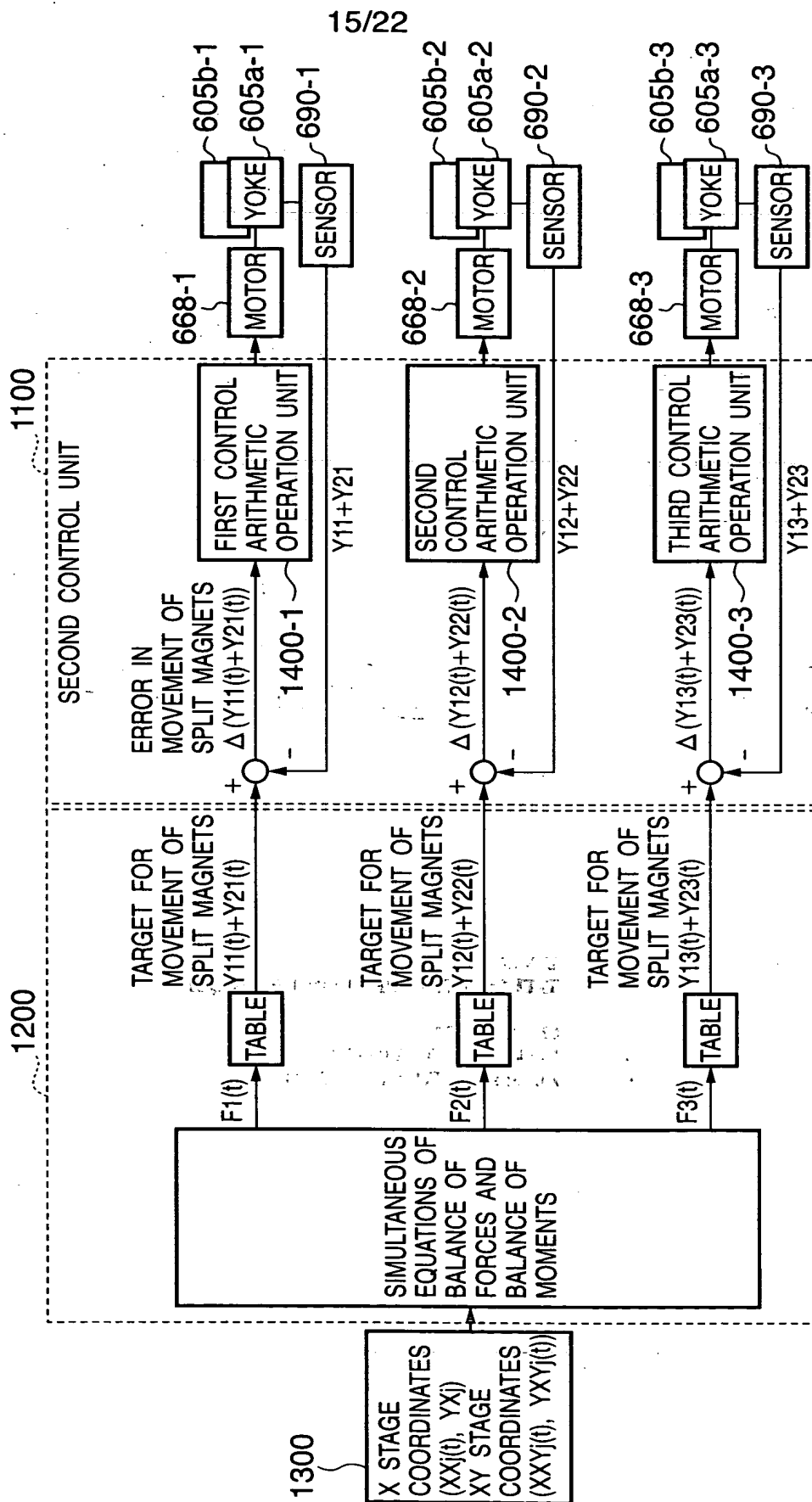


FIG. 10



# FIG. 11



# FIG. 12

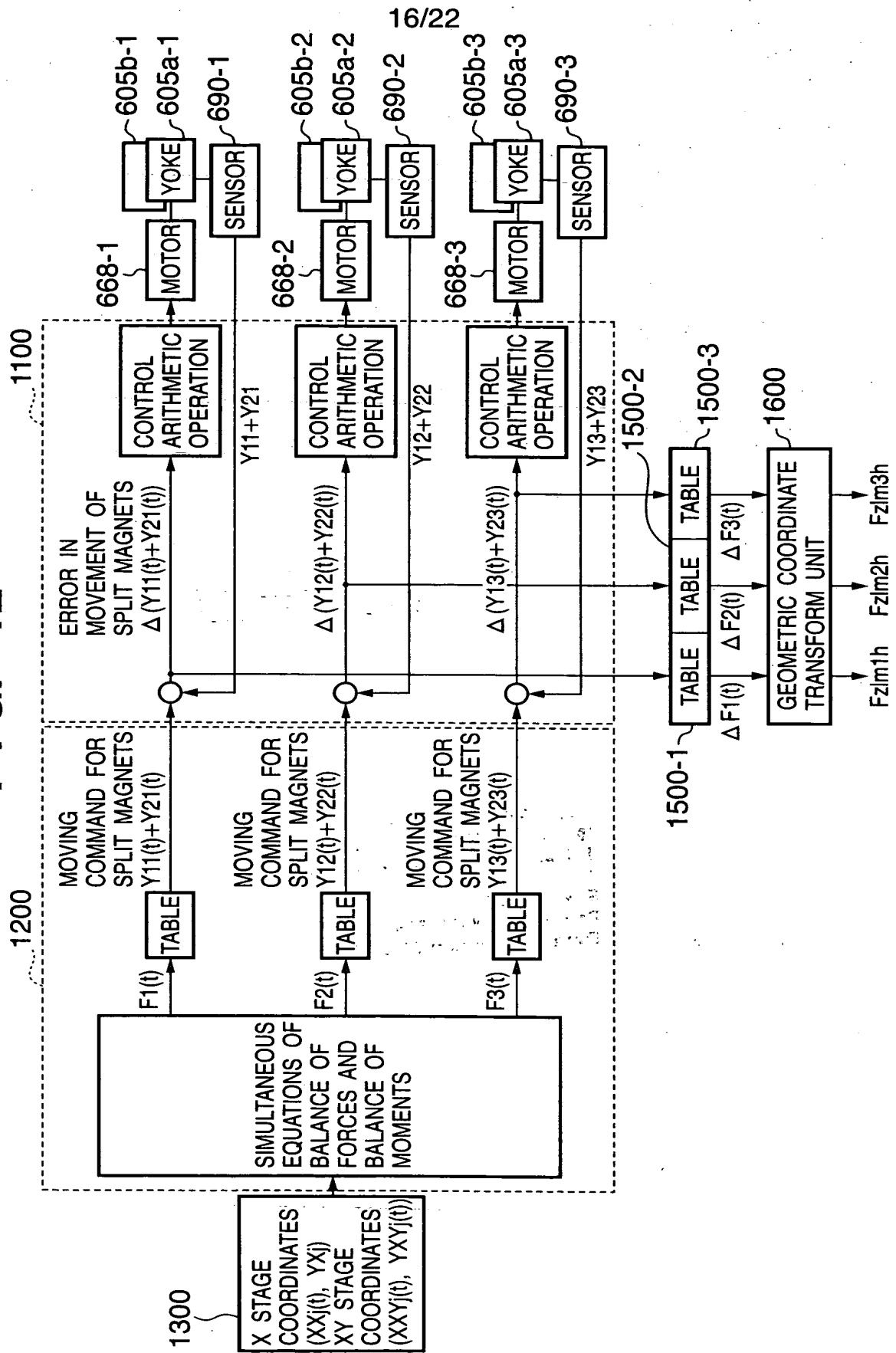




FIG. 13

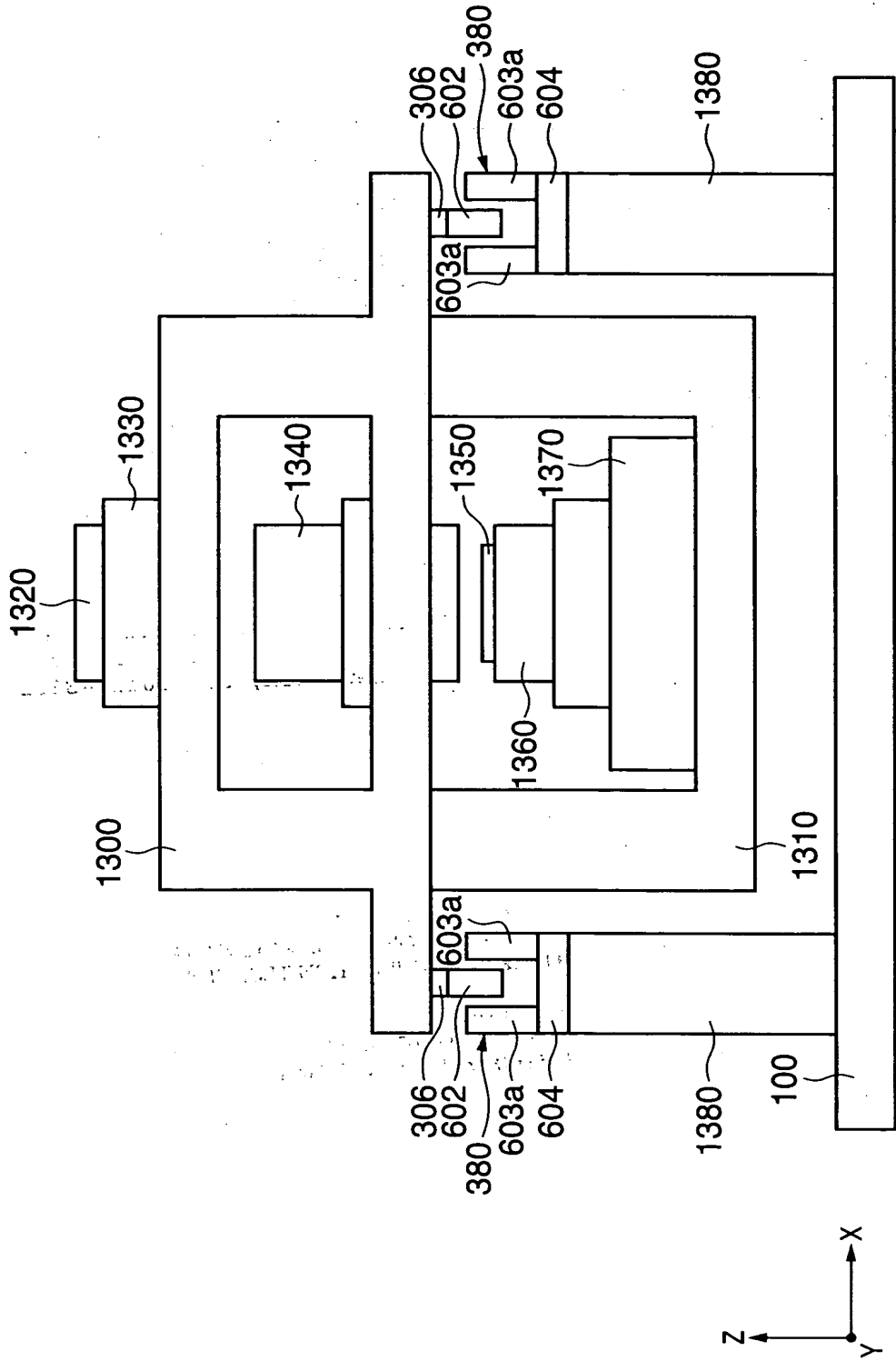


FIG. 14

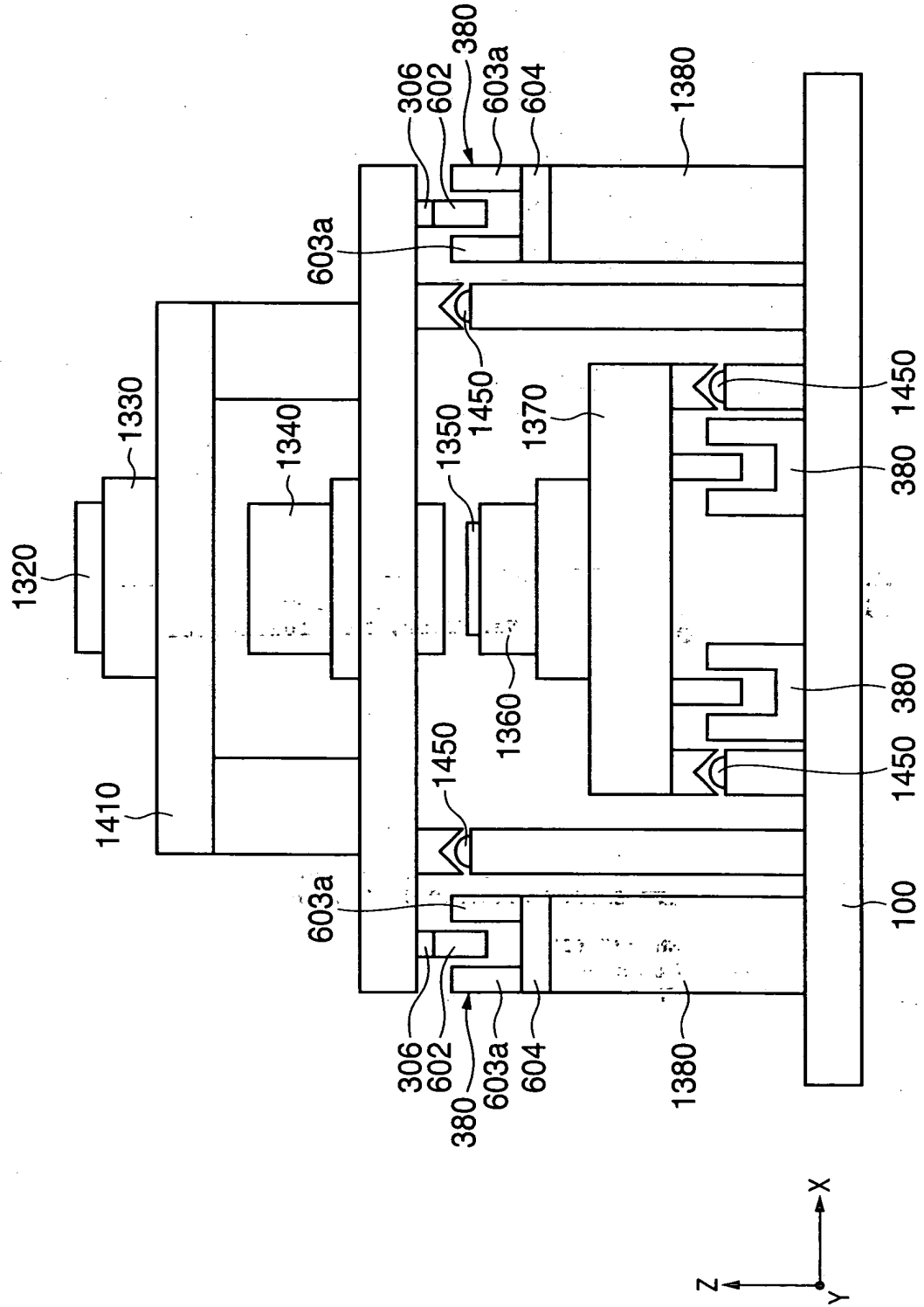
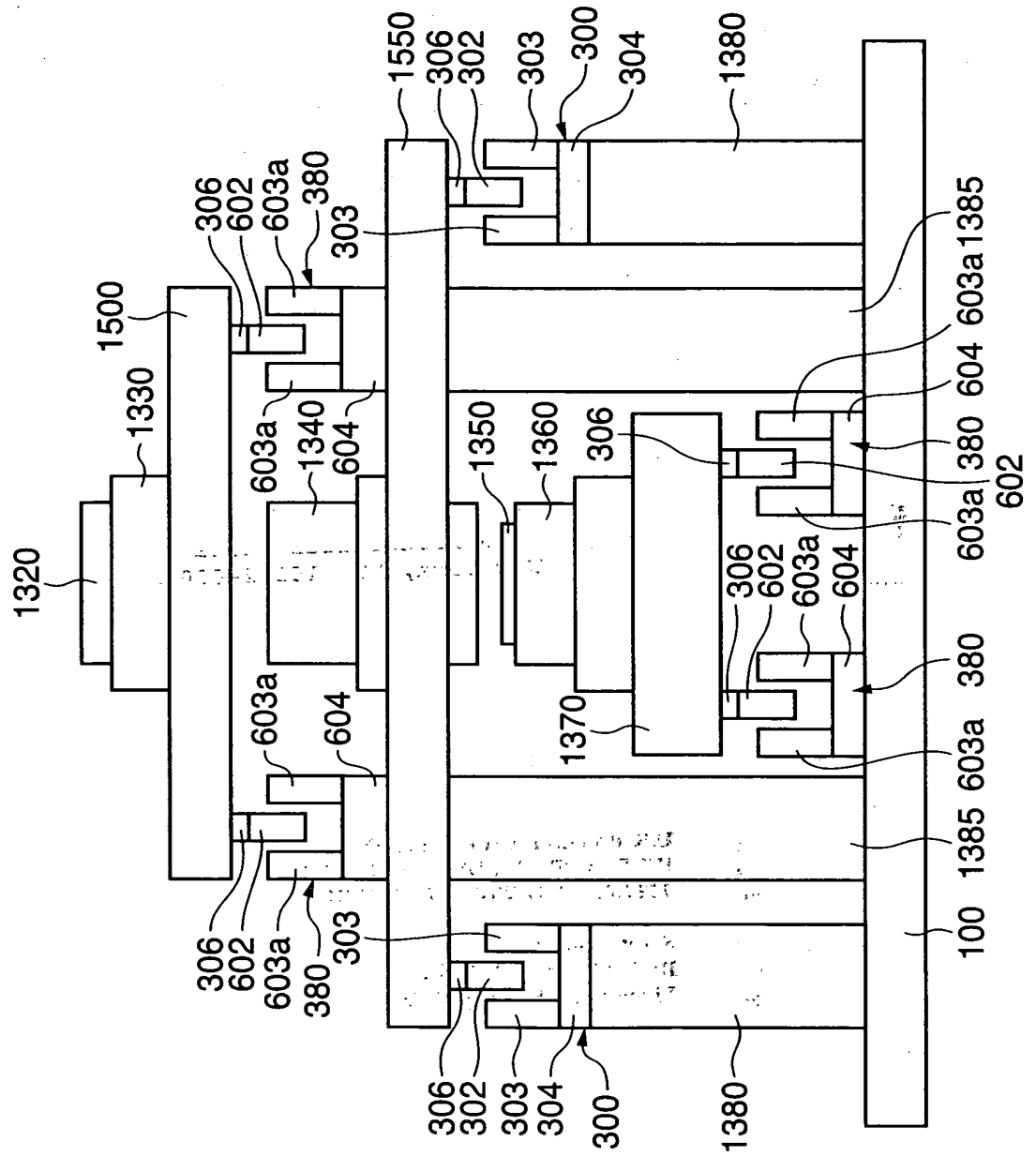
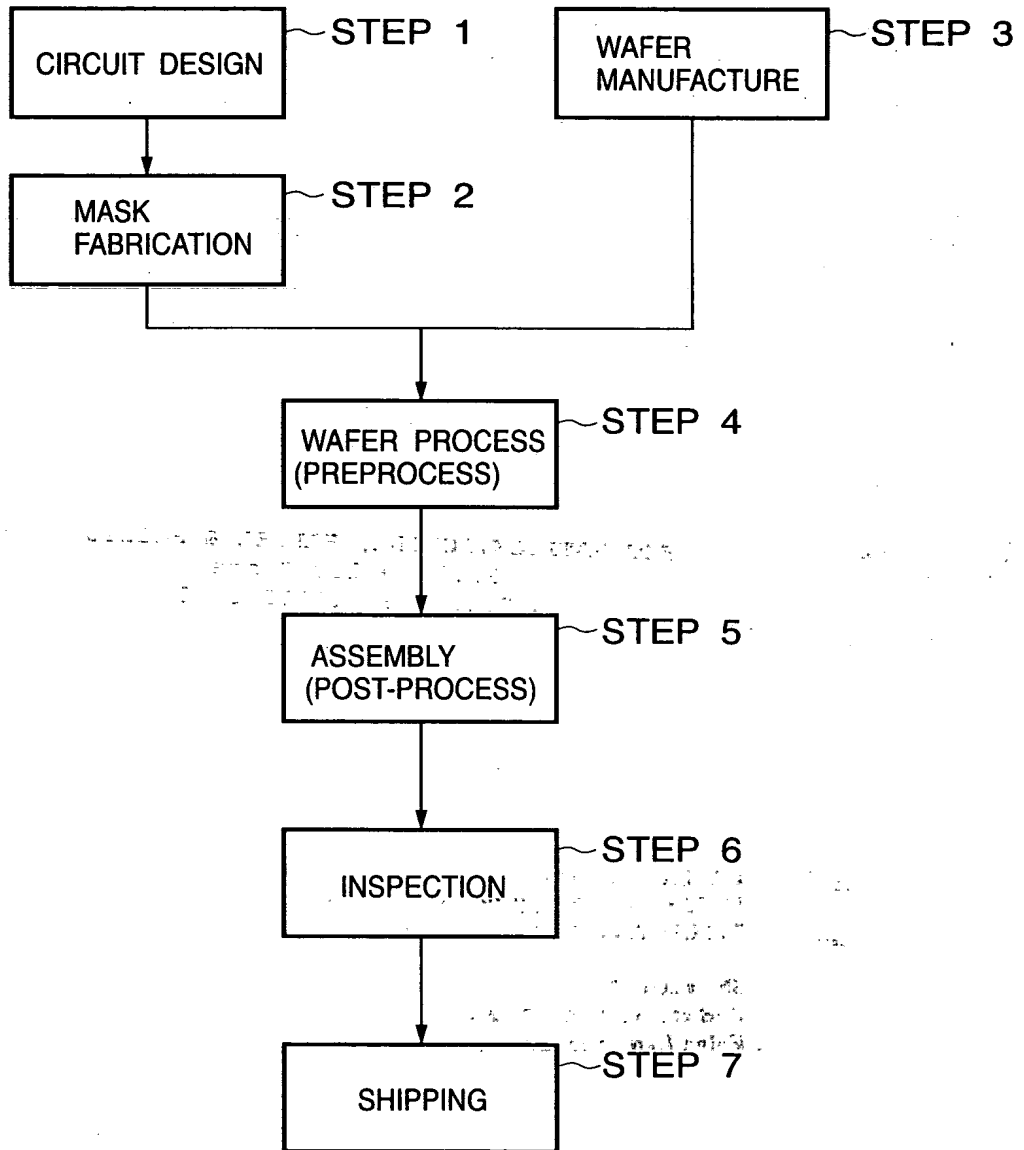


FIG. 15





**FIG. 17**

FLOW OF SEMICONDUCTOR DEVICE MANUFACTURE

FIG. 18A

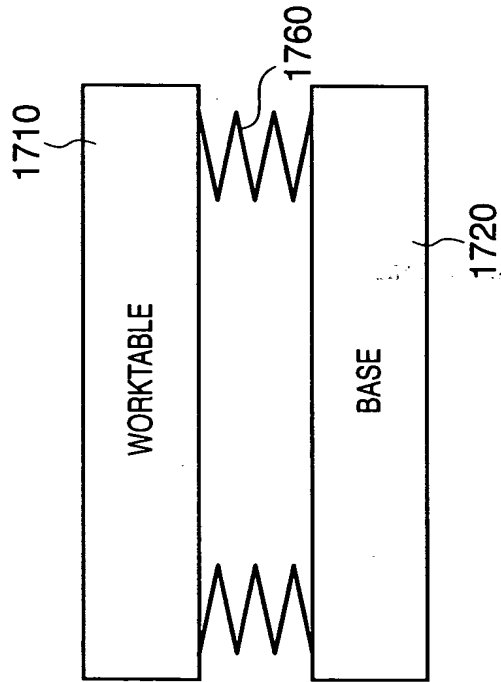


FIG. 18B

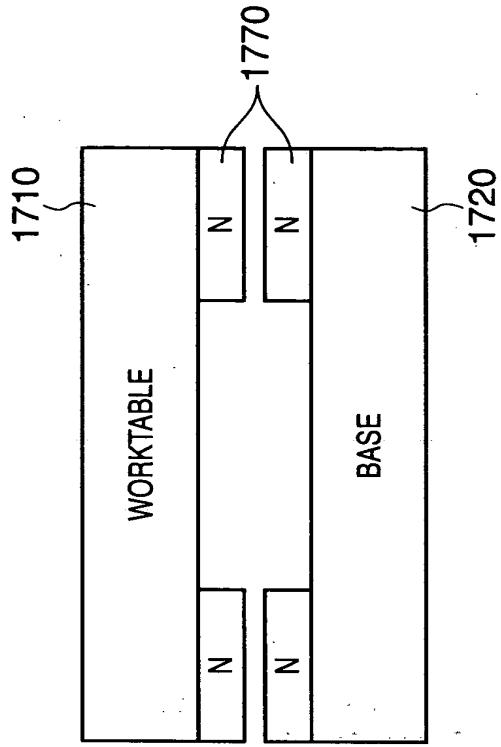


FIG. 18C

